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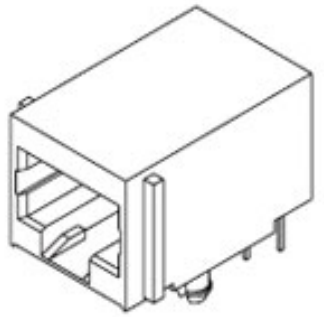
# PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

**Part Number:** 0432496101
**Status:** Active
**Overview:** modular_plugs_jacks
**Description:** Modular Jack, Right Angle, Low Profile, 6/6, Panel Stops

**Documents:**

3D Model
Drawing (PDF)
Product Specification PSX-43249 (PDF)
RoHS Certificate of Compliance (PDF)



*Series image - Reference only*

## Agency Certification

| | |
|---|---|
| CSA | LR19980 |
| UL | E107635 |

## General

| | |
|---|---|
| Product Family | Modular Jacks/Plugs |
| Series | 43249 |
| Component Type | PCB Jack |
| Magnetic | No |
| Overview | modular_plugs_jacks |
| Performance Category | 3, 4 |
| Power over Ethernet (PoE) | N/A |
| Product Name | RJ11 |

## Physical

| | |
|---|---|
| Boot Color | N/A |
| Color - Resin | Black |
| Durability (mating cycles max) | 500 |
| Flammability | 94V-0 |
| Inverted / Top Latch | No |
| Lightpipes/LEDs | None |
| Material - Metal | Phosphor Bronze |
| Material - Plating Mating | Gold |
| Material - Plating Termination | Tin |
| Material - Resin | High Temperature Thermoplastic |
| Orientation | Right Angle (Side Entry) |
| PCB Locator | Yes |
| PCB Retention | Yes |
| PCB Thickness Recommended (in) | 0.062 In |
| PCB Thickness Recommended (mm) | 1.57 mm |
| Packaging Type | Tray |
| Pitch - Mating Interface (in) | 0.040 In |
| Pitch - Mating Interface (mm) | 1.02 mm |
| Pitch - Term. Interface (in) | 0.050 In |
| Pitch - Term. Interface (mm) | 1.27 mm |
| Plating min: Mating (µin) | 50 |
| Plating min: Mating (µm) | 1.25 |
| Plating min: Termination (µin) | 100 |
| Plating min: Termination (µm) | 2.5 |
| Ports | 1 |
| Positions / Loaded Contacts | 6/6 |
| Surface Mount Compatible (SMC) | Yes |
| Temperature Range - Operating | -40°C to +85°C |
| Termination Interface: Style | Through Hole |
| Waterproof / Dustproof | No |
| Wire/Cable Type | N/A |

**EU RoHS**
**ELV and RoHS Compliant**
**REACH SVHC**
**Contains SVHC: No**
**Halogen-Free Status**
**Not Halogen-Free**

**China RoHS**

**Need more information on product environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

**Search Parts in this Series**
43249Series

**Mates With**
FCC 68 Plugs

## Electrical

| | |
|---|---|
| Current - Maximum per Contact | 1.5A |
| Shielded | No |
| Voltage - Maximum | 150V AC (RMS) |

## Solder Process Data

| | |
|---|---|
| Duration at Max. Process Temperature (seconds) | 5 |
| Lead-free Process Capability | Wave Capable (TH only) |
| Max. Cycles at Max. Process Temperature | 1 |
| Process Temperature max. C | 260 |

## Material Info

## Reference - Drawing Numbers

| | |
|---|---|
| Packaging Specification | PK-43249-004 |
| Product Specification | PSX-43249 |
| Sales Drawing | SDA-43249 |

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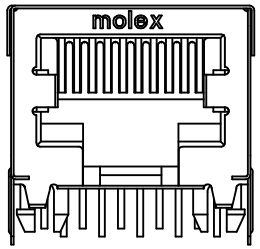
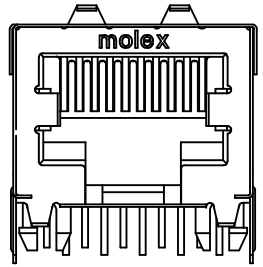
NOTES:

1) MATERIAL:
   HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
   INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
   TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
   SHIELD: BRASS, .007/(0.18) THICK
2) FINISH:
   TERMINALS:
   A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
   *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
   WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
   B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
   *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
   WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
   SHIELD:
   *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES /
   1.27 MICROMETERS COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
   *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
   DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
   CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
   IN THE PC TAILS AND/OR SHIELD.
3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.
4) PACKAGING SPECIFICATION:
   UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
   PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
   UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
   PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
   SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
   PER MOLEX PACKAGING SPECIFICATION PK-44050-004.
5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.
6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.
8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
   SPECIFICATION PS-45499-002.
10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR
    JACKS.

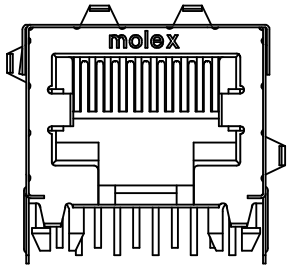
## SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



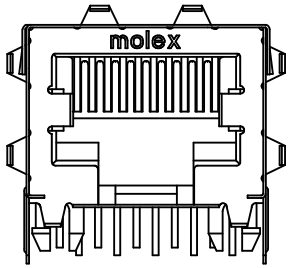

OPTION "A"
NO TOP OR SIDE TABS




OPTION "B"
TOP TABS

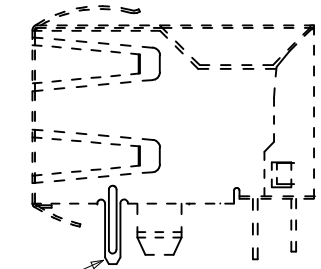



OPTION "C"
TOP AND STAGGERED SIDE TABS

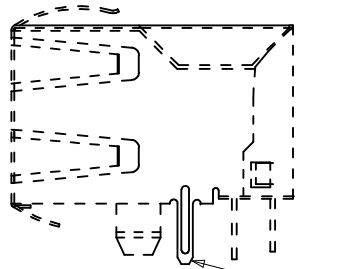



OPTION "D"
TOP AND SIDE TABS

## BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE
ON ALL SIDE/TOP TAB CONFIGURATIONS

## DRAWING LEGEND

SHEET 1- NOTES; GROUND TAB OPTIONS
SHEET 2- UNSHIELDED MODULAR JACK
SHEET 3- SHIELDED MODULAR JACK WITH OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND TAB WITH OPTIONAL POSITION.
SHEET 4- PART NUMBER CHARTS
SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

| REV | DESCRIPTION | |
|---|---|---|
| K1 | ADDED NOTE 10 | EC NO: UCP2009-0740 DRWN:JKLOSTEMEIER 2008/09/29 CHKD:JBELL 2008/10/03 APPR:FSMITH 2008/10/03 |

QUALITY SYMBOLS
▼=0
▽(C)=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ±1/2° | | |

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

| | | |
|---|---|---|
| DRAWN BY | JTR | DATE 1993/06/23 |
| CHECKED BY | JTR | DATE 1993/06/23 |
| APPROVED BY | RAS | DATE 1993/06/23 |

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

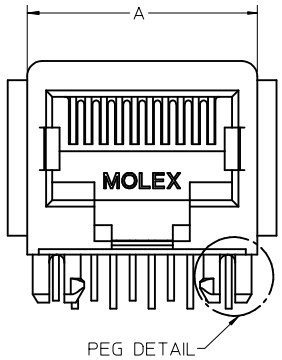
MOLEX INCORPORATED

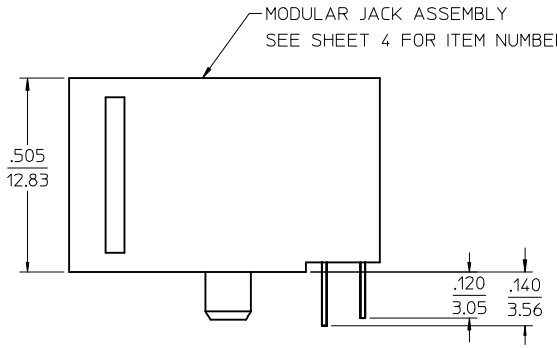
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 1 OF 6
SIZE: C

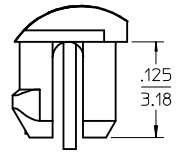
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

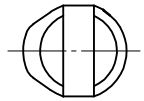
# UNSHIELDED MODULAR JACK

8 POSITION LOADED 10 SIZE SHOWN

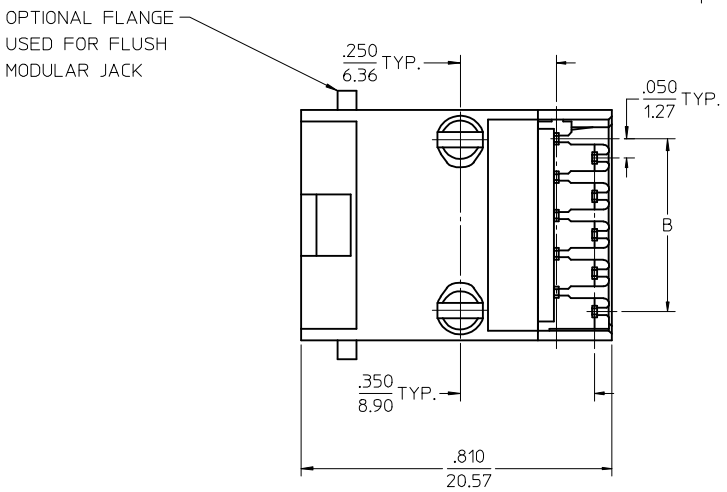


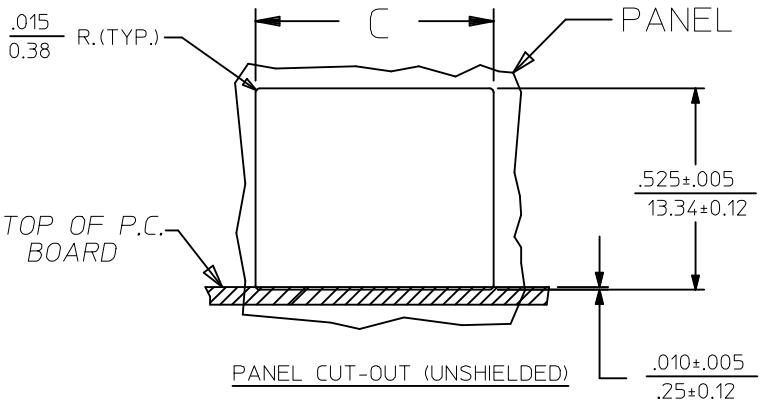



PEG DETAIL
SCALE 8:1




| HOUSING SIZE | CIRCUIT SIZE | DIM. A | DIM. B | DIM. C |
|---|---|---|---|---|
| 8 | 10 | .600±.005 (15.24±0.13) | .450±.005 (11.43±0.13) | .620±.005 (15.75±0.13) |
| 8 | 8 | .600±.005 (15.24±0.13) | .350±.005 (8.89±0.13) | .620±.005 (15.75±0.13) |
| 8 | 4 | .600±.005 (15.24±0.13) | .150±.005 (3.81±0.13) | .620±.005 (15.75±0.13) |
| 8 | 6 | .600±.005 (15.24±0.13) | .250±.005 (6.35±0.13) | .620±.005 (15.75±0.13) |
| 6 | 6 | .520±.005 (13.21±0.13) | .250±.005 (6.35±0.13) | .540±.005 (13.72±0.13) |
| 6 | 4 | .520±.005 (13.21±0.13) | .150±.005 (3.81±0.13) | .540±.005 (13.72±0.13) |
| 6 | 2 | .520±.005 (13.21±0.13) | .050±.005 (1.27±0.13) | .540±.005 (13.72±0.13) |

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CHKD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: JTR DATE: 1993/06/23
CHECKED BY: JTR DATE: 1993/06/23
APPROVED BY: RAS DATE: 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

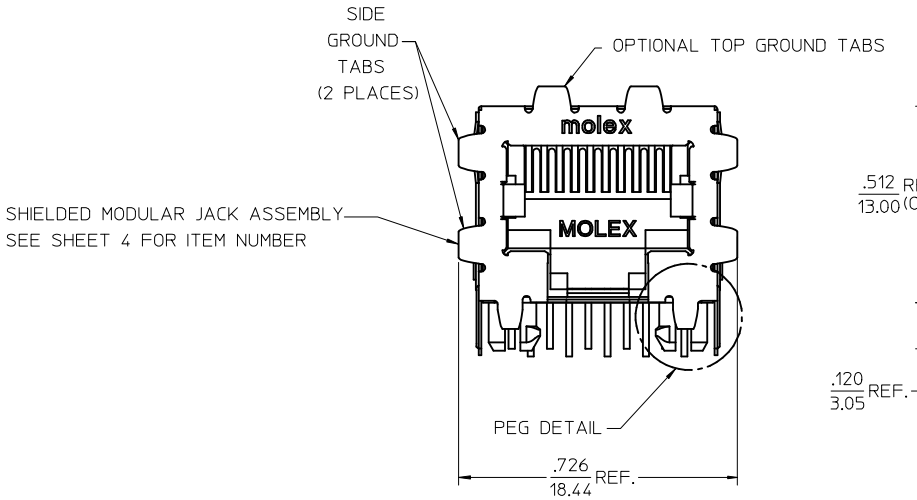
MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 2 OF 6

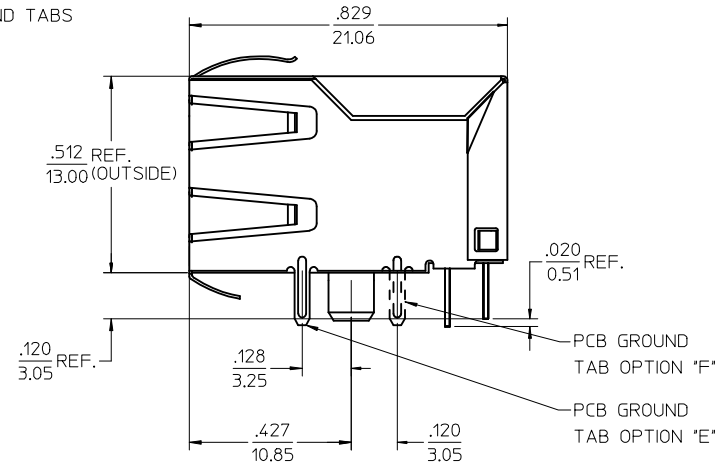
SIZE: C

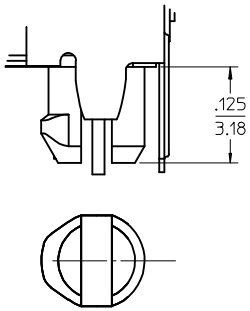
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

# MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

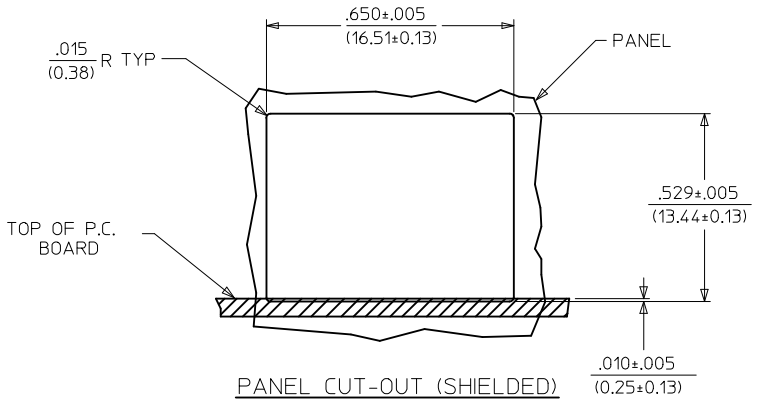
8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



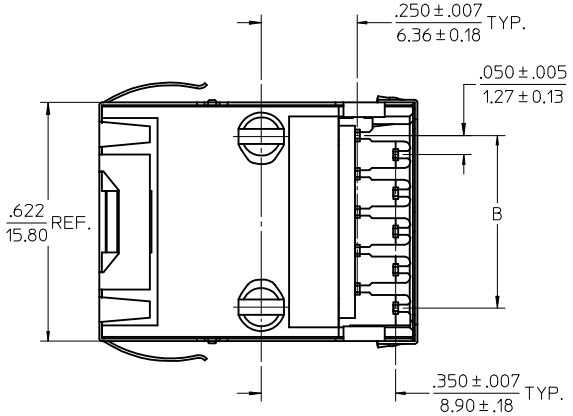




PEG DETAIL
SCALE 8:1




PANEL CUT-OUT (SHIELDED)




DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

| GROUND TAB OPTION | DESCRIPTION |
|---|---|
| A | NO GROUND TABS |
| B | TOP TABS ONLY |
| C | STAGGERED SIDE TABS |
| D | TOP AND SIDE TABS |
| E | PCB GROUND TAB IN FRONT POSITION |
| F | PCB GROUND TAB IN REAR POSITION |

| HOUSING SIZE | CIRCUIT SIZE | B |
|---|---|---|
| 8 | 10 | .450±.005 / 11.43±0.13 |
| 8 | 8 | .350±.005 / 8.89±0.13 |

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CHKD: JBELL 2008/10/03
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
Ⓒ▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

| | | DATE |
|---|---|---|
| DRAWN BY | JTR | 1993/06/23 |
| CHECKED BY | JTR | 1993/06/23 |
| APPROVED BY | RAS | 1993/06/23 |

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 3 OF 6
SIZE: C

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## FLUSH MOUNT (UNSHIELDED)

| ASSEMBLY ITEM NUMBER | CONNECTOR SIZE | NUMBER OF CIRCUITS | TERMINAL PLATING OPTION |
|---|---|---|---|
| 43249-8001 | 8 | 10 | A |
| 43249-8004 | 8 | 8 | A |
| 43249-8010 | 8 | 6 | A |
| 43249-6001 | 6 | 6 | A |
| 43249-6004 | 6 | 4 | A |
| 43249-6007 | 6 | 2 | A |

## FLANGELESS (UNSHIELDED)

| ASSEMBLY ITEM NUMBER | CONNECTOR SIZE | NUMBER OF CIRCUITS | TERMINAL PLATING OPTION |
|---|---|---|---|
| 43249-8101 | 8 | 10 | A |
| 43249-8102 | 8 | 10 | B |
| 43249-8104 | 8 | 8 | A |
| 43249-8105 | 8 | 8 | B |
| 43249-8116 | 8 | 6 | A |
| 43249-8119 | 8 | 4 | A |
| 43249-6101 | 6 | 6 | A |
| 43249-6104 | 6 | 4 | A |
| 43249-6107 | 6 | 2 | A |

## FLANGELESS (UNSHIELDED)
(SHIPPED IN TUBES)

| | | | |
|---|---|---|---|
| 43249-6501 | 6 | 6 | A |
| 43249-6504 | 6 | 4 | A |

## SHIELDED, .007" THICK

| ASSEMBLY ITEM NUMBER | CONN. SIZE | NUMBER OF CIRCUITS | TERMINAL PLATING OPTION | SIDE/TOP PANEL GROUND TAB OPTION | PCB GROUND TAB OPTION | PACKAGING OPTION |
|---|---|---|---|---|---|---|
| 43249-8900 | 8 | 10 | A | A | E | TRAY |
| 43249-8901 | 8 | 10 | A | B | E | TRAY |
| 43249-8902 | 8 | 10 | A | C | E | TRAY |
| 43249-8903 | 8 | 10 | A | D | E | TRAY |
| 43249-8908 | 8 | 10 | A | A | F | TRAY |
| 43249-8909 | 8 | 10 | A | B | F | TRAY |
| 43249-8910 | 8 | 10 | A | C | F | TRAY |
| 43249-8911 | 8 | 10 | A | D | F | TRAY |
| 43249-8916 | 8 | 8 | A | A | E | TRAY |
| 43249-8917 | 8 | 8 | A | B | E | TRAY |
| 43249-8918 | 8 | 8 | A | C | E | TRAY |
| 43249-8919 | 8 | 8 | A | D | E | TRAY |
| 43249-8920 | 8 | 8 | B | A | E | TRAY |
| 43249-8924 | 8 | 8 | A | A | F | TRAY |
| 43249-8925 | 8 | 8 | A | B | F | TRAY |
| 43249-8926 | 8 | 8 | A | C | F | TRAY |
| 43249-8927 | 8 | 8 | A | D | F | TRAY |

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CH'KD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ±1/2° | | |

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: JTR DATE: 1993/06/23
CHECKED BY: JTR DATE: 1993/06/23
APPROVED BY: RAS DATE: 1993/06/23

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SDA-43249
SHEET NO.: 4 OF 6

SIZE: C

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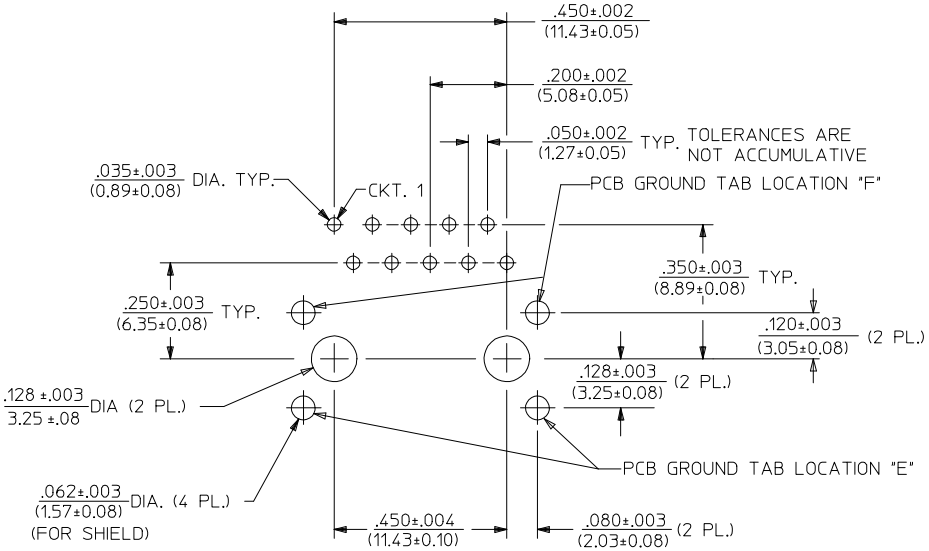
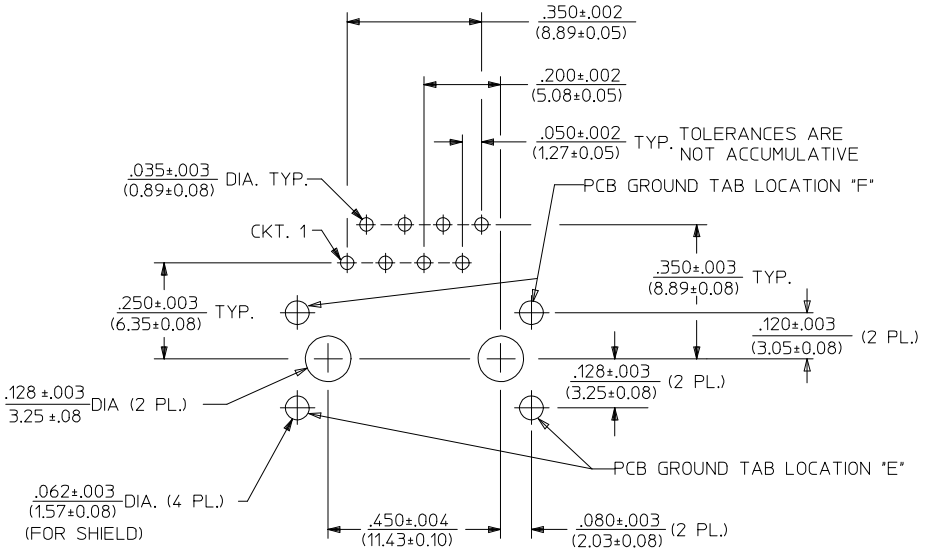


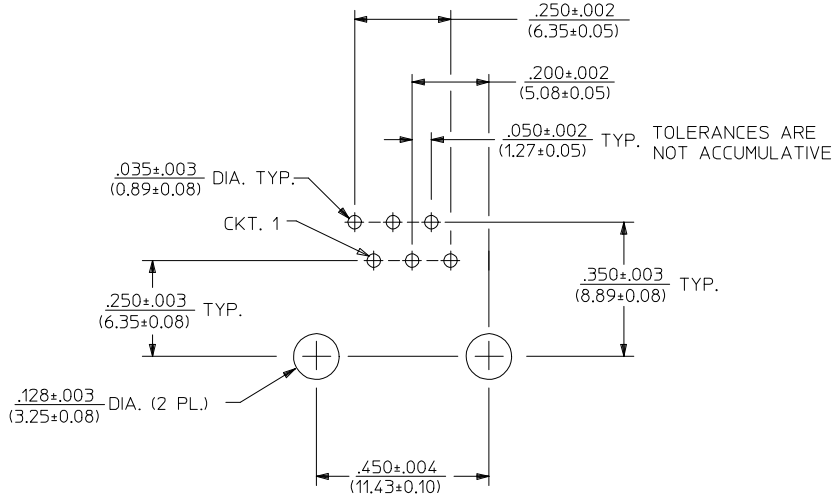

## PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT

(COMPONENT SIDE OF BOARD)




## PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT

(COMPONENT SIDE OF BOARD)




## PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CH'KD: JBELL 2008/10/03
APPR: FSMITH
DESCRIPTION
REV
K1

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ±1/2° | | |

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

| | | |
|---|---|---|
| DRAWN BY | JTR | DATE 1993/06/23 |
| CHECKED BY | JTR | DATE 1993/06/23 |
| APPROVED BY | RAS | DATE 1993/06/23 |

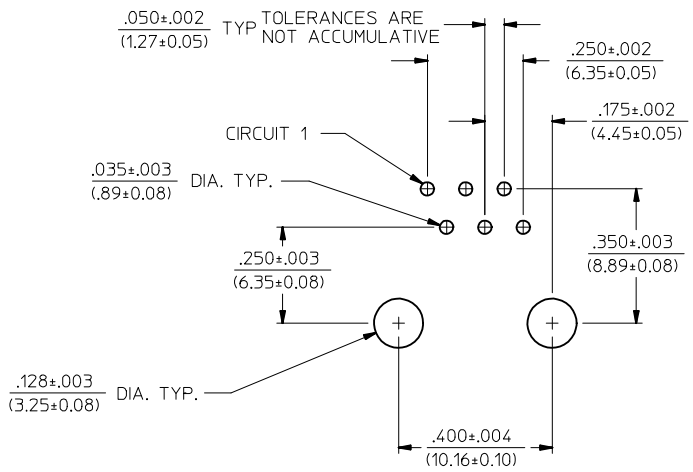
TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 5 OF 6

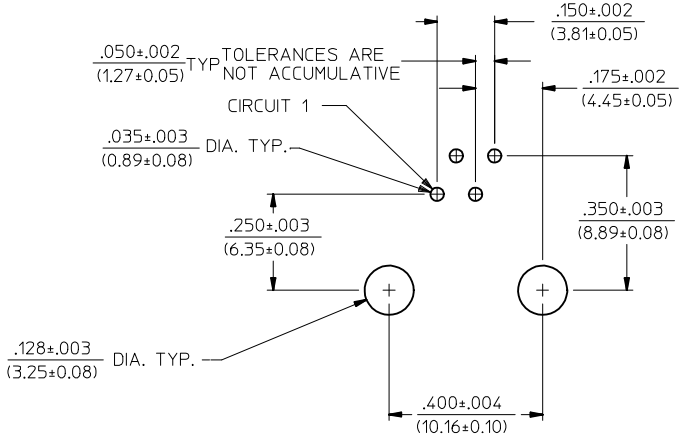
SIZE: C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



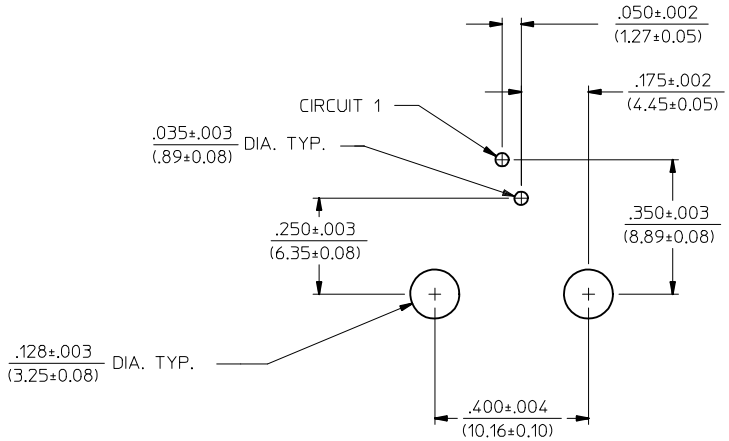

## PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT

(COMPONENT SIDE OF BOARD)




## PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT

(COMPONENT SIDE OF BOARD)




## PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT

(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1
EC NO: UCP2009-0740 2008/09/29
DRWN: JKLOSTEMEIER 2008/10/03
CH'KD: JBELL
APPR: FSMITH 2008/10/03
DESCRIPTION
K1
REV

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .010 |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ±1/2° | | |

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: IN/MM
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

| | | |
|---|---|---|
| DRAWN BY | JTR | DATE 1993/06/23 |
| CHECKED BY | JTR | DATE 1993/06/23 |
| APPROVED BY | RAS | DATE 1993/06/23 |

TITLE: LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE SHEET 4
DOCUMENT NO.: SDA-43249
SHEET NO.: 6 OF 6
SIZE: C

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LifeElectronics
Живое партнерство

**ООО «ЛайфЭлектроникс»** **“LifeElectronics” LLC**

*ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703*

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- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

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- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

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- *Входной контроль качества.*
- *Наличие сертификата ISO.*

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- *Техническую поддержку проекта.*
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- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

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*Email: org@lifeelectronics.ru*

***www.lifeelectronics.ru***